

**【1. 適用範囲 SCOPE】**

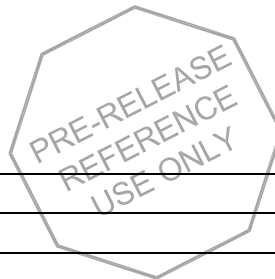
本仕様書は、\_\_\_\_\_ 殿 に納入する  
1.25 mm ピッチ 電線対基板 コネクタ (DIP R/A 品) について規定する。

This product specification covers the performance requirements for 1.25 mm PITCH WIRE TO BOARD CONNECTOR (DIP R/A TYPE) series for limited use by \_\_\_\_\_.

**【2. 製品名称及び型番 PRODUCT NAME AND PART NUMBER】**

| 製品名称<br>Product Name                          |            | 製品型番<br>Part Number |
|---|------------|---------------------|
| リセプタクル クリンプターミナル<br>Receptacle Crimp Terminal | AWG#28-#32 | 5 0 0 5 8 - 8 0 2 5 |
|   | AWG#26-#28 | 5 0 0 7 9 - 8 0 2 5 |
| リセプタクル ハウジング<br>Receptacle Housing            |            | 5 1 0 2 1 - * * 0 0 |
| ヘッダー アッセンブリ<br>Header Assembly (DIP R/A)      |            | 5 3 0 4 8 - * * 5 0 |

\* : 図面参照 Refer to the drawing.



|                                 |  |        |  |                     |                         |                     |
|---------------------------------|--|--------|--|---------------------|-------------------------|---------------------|
| REV.                            | A  | B      |  |                     |                         |                     |
| SHEET                           | 1-14   | 1-14   |  |                     |                         |                     |
| REVISE ON PC ONLY               |  |        | TITLE:   |                     |                         |                     |
| <b>B</b>                        | 変更<br>REVISED<br>611272<br>2018/01/30 S.OBARA  |        | PicoBlade 1.25<br>DIP R/A 0.38µm GOLD PLATING TYPE |                     |                         |                     |
|                                 | THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION |        |  |                     |                         |                     |
| REV.                            | DESCRIPTION  |        |  |                     |                         |                     |
| DESIGN CONTROL<br>J             |  | STATUS | WRITTEN BY:<br>SOBARA01                            | CHECKED BY:<br>AIDA | APPROVED BY:<br>TKANEKO | DATE:<br>2017/10/12 |
| DOCUMENT NUMBER<br>510210000-PS |  |        | DOC. TYPE<br>PS                                    | DOC. PART<br>000    | CUSTOMER<br>GENERAL     | SHEET<br>1 OF 15    |

**【3. 定格及び適用電線 RATINGS AND APPLICABLE WIRES】**

| 項目<br>Item   | 規格<br>Standard                |       |   |
|--|-------------------------------|-------|---|
| 最大許容電圧<br>Rated Voltage (MAX.)                                   | 125 V (実効値 rms)               |       | [AC(実効値 rms) / DC]  |
| 最大許容電流<br>及び適用電線<br>Rated Current (MAX.)<br>and Applicable wires | AWG. #26                      | 1.0 A | 被覆外径<br>Insulation O.D<br>50058-8025: : $\phi$ 1.0mm MAX.<br>50079-8025: : $\phi$ 1.04mm MAX. |
|  | AWG. #28                      | 1.0 A |   |
|  | AWG. #30                      | 1.0 A |   |
|  | AWG. #32                      | 0.8 A |   |
| 使用温度範囲 <sup>*1</sup><br>Ambient Temperature Range                | -40°C ~ +105°C <sup>*2*</sup> |       |   |

\*1: 基板実装後の無通電状態は、使用温度範囲が適用されます。

Non-operating connectors after reflow must follow the operating temperature range condition.

\*2: 通電による温度上昇分も含む。 Including terminal temperature rise.

\*3: 適合電線も本使用温度範囲を満足すること。

Applicable wires must also meet the specified temperature range.

**参考許容電流 CURRENT DERATING REFERENCE INFORMATION**

| AWG | 2-circuits | 8-circuits | 15-circuits |
|-----|------------|------------|-------------|
|     | Amps (A)   | Amps (A)   | Amps (A)    |
| 26  | 2.5        | 1.5        | 1.0         |
| 28  | 2.0        | 1.5        | 1.0         |
| 30  | 1.5        | 1.0        | 1.0         |
| 32  | 1.5        | 1.0        | 0.8         |

1) 各電流値は参考となります。

Values are for REFERENCE ONLY

2) 閾値は温度上昇30°C以下としています。

Current deratings are based on not exceeding 30°C Temperature Rise.

3) 温度上昇の測定は圧着端子のバレル部にて実施しています。

Temperature Rise is measured in barrel area of crimp terminal.

4) 基板デザインにより温度上昇の結果が異なります。

PCB trace design can greatly affect temperature rise results.

5) 全極に通電し測定しています。

Data is for all circuits powered.



|                                 |                   |  |  |                     |                  |
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【4. 性能 PERFORMANCE】

4-1. 電気的性能 Electrical Performance

| 項目<br>Item |  | 条件<br>Test Condition   | 規格<br>Requirement                           |
|------------|--|--|---|
| 4-1-1      | 接触抵抗<br>Contact Resistance                       | コネクタを嵌合させ、開放電圧 20mV 以下、短絡電流 10mA 以下にて測定する。(JIS C5402-2-1)<br>Mate connectors, and measure by dry circuit, 20mV MAX., 10mA MAX. (JIS C5402-2-1)   | 20 mΩ MAX.                                  |
| 4-1-2      | 絶縁抵抗<br>Insulation Resistance                    | コネクタを嵌合させ、隣接するターミナル間 及びターミナル、アース間に、DC 500V を印加し測定する。(JIS C5402-3-1/MIL-STD-202 試験法 302)<br>Mate connectors, apply 500V DC between adjacent terminal or ground.<br>(JIS C5402-3-1/MIL-STD-202 Method 302)                                   | 100 MΩ MIN.                                 |
| 4-1-3      | 耐電圧<br>Dielectric Strength                       | コネクタを嵌合させ、隣接するターミナル間 及びターミナル、アース間に、AC(rms) 250V (実効値) を1分間 印加する。<br>(JIS C5402-4-1/MIL-STD-202 試験法 301)<br>Mate connectors, apply 250V AC(rms) for 1 minute between adjacent terminal or ground.<br>(JIS C5402-4-1/MIL-STD-202 Method 301) | 製品機能を損なう<br>異常なきこと<br>No Damage on function |
| 4-1-4      | 圧着部接触抵抗<br>Contact Resistance on Crimped Portion | ターミナルに適合電線を圧着し、開放電圧20mV以下、短絡電流 10mA 以下にて測定する。<br>Crimp the applicable wire to the terminal, measured by dry circuit, 20mV MAX., 10mA.MAX.  | 5 mΩ MAX.                                   |



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| EN-127(2015-12)                 |                   |  |                  |                     |

4-2. 機械的性能 Mechanical Performance

| 項目<br>Item |   | 条件<br>Test Condition   | 規格<br>Requirement              |                      |
|------------|---|--|--------------------------------|----------------------|
| 4-2-1      | 挿入力<br>及び抜去力<br>Insertion and<br>Withdrawal Force | 毎分 25±3mm の速さで挿入、抜去を行う。<br>Insert and withdraw connectors at the speed<br>rate of 25±3mm/minute.   | 第 6 参照<br>Refer to paragraph 6 |                      |
| 4-2-2      | 圧着部引張強度<br>Crimping<br>Pull out Force             | 圧着されたターミナルを治具に固定し、<br>電線を軸方向に毎分25±3mmの速さで引張る。<br>(JIS C5402-16-4)<br><br>Fix the crimped terminal to the jig, apply axial<br>pull out force on the wire at the speed rate of 25<br>±3 mm/minute.<br>(JIS C5402-16-4) | AWG. #26                       | 19.6 N {2.0kgf} MIN. |
|            |   |  | AWG. #28                       | 9.8 N {1.0kgf} MIN.  |
|            |   |  | AWG. #30                       | 4.9 N {0.5kgf} MIN.  |
|            |   |  | AWG. #32                       | 3.4 N {0.3kgf} MIN.  |
| 4-2-3      | 圧着端子挿入力<br>Crimp Terminal<br>Insertion Force      | 圧着されたターミナルをハウジングに挿入す<br>る。<br>Insert the crimped terminal into the housing.  | 4.9 N {0.5kgf} MAX.            |                      |
| 4-2-4      | 圧着端子保持力<br>Crimp Terminal<br>Retention Force      | 圧着されたターミナルをハウジングに装着し、<br>電線を軸方向に毎分 25±3mm の速さで引張<br>る。<br><br>Apply axial pull out force to the terminal<br>assembled in the housing at the speed rate of<br>25±3mm/minute.  | 4.9 N {0.5kgf} MIN.            |                      |
| 4-2-5      | HDR端子保持力<br>Header Terminal<br>Retention Force    | ハウジングに圧入されたターミナルを毎分<br>25±3mm の速さで軸方向に押す。<br><br>Apply axial push out force at the speed rate of<br>25±3 mm/minute on the terminal assembled in<br>the housing.  | 4.9 N {0.5kgf} MIN.            |                      |



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|-------------------|-------------------|---|-----------|----------|---------|
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| <b>B</b>          | SEE SHEET 1 OF 15 | PicoBlade 1.25<br>DIP R/A 0.38µm GOLD PLATING TYPE  |           |          |         |
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4-3. 環境性能、その他 Environmental Performance and Others

| 項目<br>Item |   | 条件<br>Test Condition  | 規格<br>Requirement          |   |
|------------|---|---|----------------------------|---|
| 4-3-1      | 繰り返し挿抜<br>Repeated Insertion/<br>Withdrawal | 1分間10回以下の速さで、挿入、抜去を30回繰返す。<br>Insert and withdraw connectors 30 cycles repeatedly by rate of less than 10 cycles per minute.  | 接触抵抗<br>Contact Resistance | 40 mΩ MAX.                              |
| 4-3-2      | 温度上昇<br>Temperature Rise                    | コネクタを嵌合させ、全ての圧着端子を直列に接続し最大許容電流で熱平衡に達した時の温度上昇を測定する。(UL498)<br>Mate connectors and all crimp terminals shall be connected in a direct series. The temperature rise shall be measured when the terminal reaches terminal equilibrium allowable current. (UL498)  | 温度上昇<br>Temperature Rise   | 30°C MAX.                               |
| 4-3-3      | 耐振動性<br>Vibration                           | コネクタを嵌合させ、DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な 3方向に 掃引割合 10~55~10 Hz/分、全振幅 1.5mm の振動を各 2時間 加える。(ケーブルは固定すること)<br>(JIS C 60068-2-6/MIL-STD-202 試験法 201)<br>Mate connectors and subject to the following vibration conditions, for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1mA during the test. (Fix the cable at test.)<br>Amplitude : 1.5mm P-P<br>Frequency : 10~55~10 Hz in 1 minute.<br>Duration : 2 hours in each X.Y.Z.axes.<br>(JIS C 60068-2-6/MIL-STD-202 Method 201) | 外観<br>Appearance           | 製品機能を損なう異常なきこと<br>No Damage on function |
|            |   |   | 接触抵抗<br>Contact Resistance | 40 mΩ MAX.                              |
|            |   |   | 瞬断<br>Discontinuity        | 1 μsec. MAX.                            |
| 4-3-4      | 耐衝撃性<br>Mechanical Shock                    | コネクタを嵌合させ、DC 1mA 通電状態にて、テストパルス半周期、嵌合軸を含む互いに垂直な 6方向に 490m/s <sup>2</sup> { 50G }、作用時間11ms の衝撃を各3回、合計18回加える。<br>(JIS C60068-2-27/MIL-STD-202 試験法 213)<br>Mate connectors and subject to the following shock conditions. 3 shocks shall be applied along 3 mutually perpendicular axes, passing DC 1 mA current during the test.<br>(Total of 18 shocks)<br>Test pulse : Half Sine<br>Peak value : 490 m/s <sup>2</sup> (50 G)<br>Duration : 11 ms<br>(JIS C60068-2-27/MIL-STD-202 Method 213)         | 外観<br>Appearance           | 製品機能を損なう異常なきこと<br>No Damage on function |
|            |   |   | 接触抵抗<br>Contact Resistance | 40 mΩ MAX.                              |
|            |   |   | 瞬断<br>Discontinuity        | 1 μsec. MAX.                            |

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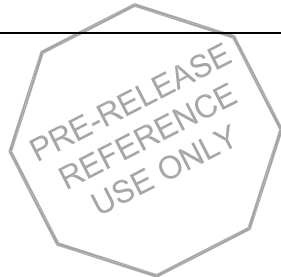
| 項 目<br>Item |                        | 条 件<br>Test Condition  | 規 格<br>Requirement               |   |
|-------------|------------------------|--|----------------------------------|---|
| 4-3-5       | 耐熱性<br>Heat Resistance | コネクタを嵌合させ、105±2°C の雰囲気中に96時間放置後取り出し、1~2時間室温に放置する。<br>(JIS C60068-2-2/MIL-STD-202 試験法 108)<br><br>Mate connectors and expose to 105±2°C for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours , after which the specified measurements shall be performed.<br>(JIS C60068-2-2/MIL-STD-202 Method 108)   | 外 観<br>Appearance                | 製品機能を損なう異常なきこと<br>No Damage on function |
|             |                        |  | 接 触 抵 抗<br>Contact Resistance    | 40 mΩ MAX.                              |
| 4-3-6       | 耐寒性<br>Cold Resistance | コネクタを嵌合させ、-40±3°C の雰囲気中に96時間 放置後取り出し、1~2時間 室温に放置する。(JIS C60068-2-1)<br><br>Mate connectors and expose to -40±3°C for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>(JIS C60068-2-1)   | 外 観<br>Appearance                | 製品機能を損なう異常なきこと<br>No Damage on function |
|             |                        |  | 接 触 抵 抗<br>Contact Resistance    | 40 mΩ MAX.                              |
| 4-3-7       | 耐湿性<br>Humidity        | コネクタを嵌合させ、60±2°C、相対湿度90~95% の雰囲気中に 96時間 放置後取り出し、1~2時間 室温に放置する。<br>(JIS C60068-2-78/MIL-STD-202 試験法 103)<br><br>Mate connectors and expose to 60±2°C, relative humidity 90 to 95% for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>(JIS C60068-2-78/MIL-STD-202 Method 103) | 外 観<br>Appearance                | 製品機能を損なう異常なきこと<br>No Damage on function |
|             |                        |  | 接 触 抵 抗<br>Contact Resistance    | 40 mΩ MAX.                              |
|             |                        |  | 絶 縁 抵 抗<br>Insulation Resistance | 10 MΩ MIN.                              |
|             |                        |  | 耐 電 圧<br>Dielectric Strength     | 4-1-3項満足のこと<br>Must meet 4-1-3          |



|                   |                   |  |
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| 項 目<br>Item |                                  | 条 件<br>Test Condition   | 規 格<br>Requirement               |   |
|-------------|----------------------------------|---|----------------------------------|---|
| 4-3-8       | 温度サイクル<br>Temperature<br>Cycling | コネクタを嵌合させ、 $-55\pm 3^{\circ}\text{C}$ に30分、 $+105\pm 2^{\circ}\text{C}$ に 30分。これを1サイクルとし、5サイクル繰返す。但し、温度移行時間は5分以内 とする。<br>試験後1~2時間 室温に放置する。<br>(JIS C60068-2-14)<br><br>Mate connectors and subject to the following conditions for 5 cycles. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>5 cycles of :<br>a) $-55\pm 3^{\circ}\text{C}$ 30 minutes<br>b) $+105\pm 2^{\circ}\text{C}$ 30 minutes<br>Shift time : Within 5 minutes<br>(JIS C60068-2-14)                        | 外 観<br>Appearance                | 製品機能を損なう異常なきこと<br>No Damage on function |
|             |                                  |   | 接 触 抵 抗<br>Contact<br>Resistance | 40 mΩ MAX.                              |
| 4-3-9       | 塩水噴霧<br>Salt Spray               | コネクタを嵌合させ、 $35\pm 2^{\circ}\text{C}$ にて $5\pm 1\%$ 重量比の塩水を $48\pm 4$ 時間噴霧し、試験後常温で水洗いした後、室温で乾燥させる。<br>(JIS C60068-2-11/MIL-STD-202 試験法101)<br><br>Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water, after which the specified measurements shall be performed.<br>NaCl solution<br>Concentration                      : $5\pm 1\%$<br>Spray time                            : $48\pm 4$ hours<br>Ambient temperature : $35\pm 2^{\circ}\text{C}$<br>(JIS 60068-2-11/MIL-STD-202 Method 101) | 外 観<br>Appearance                | 製品機能を損なう異常なきこと<br>No Damage on function |
|             |                                  |   | 接 触 抵 抗<br>Contact<br>Resistance | 40 mΩ MAX.                              |



|                   |                   |  |           |          |         |
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| 項 目<br>Item |                                | 条 件<br>Test Condition   | 規 格<br>Requirement            |   |
|-------------|--------------------------------|---|-------------------------------|---|
| 4-3-10      | 耐亜硫酸ガス<br>SO <sub>2</sub> Gas  | コネクタを嵌合させ、40±2°Cにて50±5ppmの亜硫酸ガス中に24時間放置する。<br><br>Mated connectors and expose to the conditions of 50±5ppm SO <sub>2</sub> gas ambient temperature 40±2°C for 24 hours.   | 外 観<br>Appearance             | 製品機能を損なう異常なきこと<br>No Damage on function |
|             |                                |   | 接 触 抵 抗<br>Contact Resistance | 40 mΩ MAX.                              |
| 4-3-11      | 耐アンモニア性<br>NH <sub>3</sub> Gas | コネクタを嵌合させ、濃度28%のアンモニア水を入れた容器中に40分間放置する。<br>(1Lに対して25mLの割合)<br>Mated connectors and expose to the conditions of NH <sub>3</sub> gas evaporating from 28% NH <sub>3</sub> solution for 40 minutes.<br>(Rate is 25ml per 1L) | 外 観<br>Appearance             | 製品機能を損なう異常なきこと<br>No Damage on function |
|             |                                |   | 接 触 抵 抗<br>Contact Resistance | 40 mΩ MAX.                              |



|                                 |                   |  |  |                     |                  |
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| 項 目<br>Item |  | 条 件<br>Test Condition  | 規 格<br>Requirement    |   |
|-------------|--|--|-----------------------|---|
| 4-3-12      | はんだ付け性<br>Solderability                | ターミナルまたはピンを本体取付け基準面より0.8mm迄、245±3°Cのはんだに3±0.5秒浸す。<br><br>Dip terminal or pin into immerse the area up to 1.2mm from the bottom of the housing into solder molten at 245±3°C for 3±0.5 sec.   | 濡れ性<br>Solder Wetting | ピンホールや隙間なく浸漬面積の95%以上<br>95% of immersed area must show no voids, pin holes. |
| 4-3-13      | はんだ耐熱性<br>Resistance to Soldering Heat | <u>ディップの場合</u><br><u>Soldering bath method</u><br>ターミナルまたはピンを本体取付け基準面より0.8mm迄、260±5°Cのはんだに10±0.5秒浸す。<br>Dip terminal or pin into immerse the area up to 0.8mm from the bottom of the housing into solder molten at 260±5°C for 10±0.5 sec. | 外 観<br>Appearance     | 端子ガタ、割れ等製品機能を損なう異常なきこと<br>No Damage on function                             |
|             |  | <u>手はんだ時</u><br><u>(Reflow by Manual Soldering iron)</u><br>350±10°Cのはんだゴテにて最大5秒加熱する。但し、端ピンに異常な加圧のないこと。<br>Using a soldering iron (350±10°C for 5 seconds MAX.) heat up. However, do not apply excessive pressure to either the terminals. |                       |   |

( ): 参考規格 Reference Standard

{ }: 参考単位 Reference Unit

【5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS】

5-1. 製品寸法及び材質 Dimensions and materials of product.

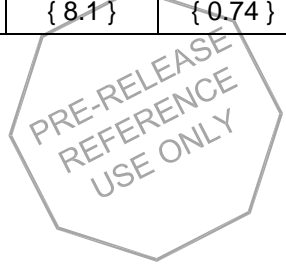
図面参照 Refer to the drawing.



|                   |                   |  |           |          |         |
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【6. 挿入力及び抜去力 INSERTION / WITHDRAWAL FORCE】

| 極数<br>No. of<br>CKT. | 単位<br>Unit   | 挿入力（最大値）<br>Insertion force (MAX.) |                 |                 | 抜去力（最小値）<br>Withdrawal force (MIN.) |                 |                 |
|----------------------|--------------|------------------------------------|-----------------|-----------------|-------------------------------------|-----------------|-----------------|
|                      |              | 初回<br>1st                          | 6回目<br>6th      | 30回目<br>30th    | 初回<br>1st                           | 6回目<br>6th      | 30回目<br>30th    |
| 2                    | N<br>{ kgf } | 19.6<br>{ 2.0 }                    | 17.6<br>{ 1.8 } | 15.6<br>{ 1.6 } | 2.8<br>{ 0.28 }                     | 2.3<br>{ 0.23 } | 1.8<br>{ 0.18 } |
| 3                    | N<br>{ kgf } | 24.5<br>{ 2.5 }                    | 22.5<br>{ 2.3 } | 20.5<br>{ 2.1 } | 3.0<br>{ 0.30 }                     | 2.5<br>{ 0.25 } | 2.0<br>{ 0.20 } |
| 4                    | N<br>{ kgf } | 29.4<br>{ 3.0 }                    | 27.4<br>{ 2.8 } | 25.4<br>{ 2.6 } | 3.3<br>{ 0.33 }                     | 2.8<br>{ 0.28 } | 2.3<br>{ 0.23 } |
| 5                    | N<br>{ kgf } | 34.3<br>{ 3.5 }                    | 32.3<br>{ 3.3 } | 30.3<br>{ 3.1 } | 3.8<br>{ 0.38 }                     | 3.3<br>{ 0.33 } | 2.8<br>{ 0.28 } |
| 6                    | N<br>{ kgf } | 39.2<br>{ 4.0 }                    | 37.2<br>{ 3.8 } | 35.2<br>{ 3.6 } | 4.3<br>{ 0.43 }                     | 3.8<br>{ 0.38 } | 3.3<br>{ 0.33 } |
| 7                    | N<br>{ kgf } | 44.1<br>{ 4.5 }                    | 42.1<br>{ 4.3 } | 40.1<br>{ 4.1 } | 4.7<br>{ 0.48 }                     | 4.3<br>{ 0.43 } | 3.8<br>{ 0.38 } |
| 8                    | N<br>{ kgf } | 49.0<br>{ 5.0 }                    | 47.0<br>{ 4.8 } | 45.0<br>{ 4.6 } | 5.2<br>{ 0.53 }                     | 4.7<br>{ 0.48 } | 4.3<br>{ 0.43 } |
| 9                    | N<br>{ kgf } | 53.9<br>{ 5.5 }                    | 51.9<br>{ 5.3 } | 49.9<br>{ 5.1 } | 5.5<br>{ 0.56 }                     | 5.0<br>{ 0.51 } | 4.5<br>{ 0.46 } |
| 10                   | N<br>{ kgf } | 58.8<br>{ 6.0 }                    | 56.8<br>{ 5.8 } | 54.8<br>{ 5.6 } | 5.8<br>{ 0.59 }                     | 5.3<br>{ 0.54 } | 4.8<br>{ 0.49 } |
| 11                   | N<br>{ kgf } | 63.7<br>{ 6.5 }                    | 61.7<br>{ 6.3 } | 59.7<br>{ 6.1 } | 6.1<br>{ 0.62 }                     | 5.6<br>{ 0.57 } | 5.1<br>{ 0.52 } |
| 12                   | N<br>{ kgf } | 68.6<br>{ 7.0 }                    | 66.6<br>{ 6.8 } | 64.6<br>{ 6.6 } | 6.4<br>{ 0.65 }                     | 5.9<br>{ 0.60 } | 5.4<br>{ 0.55 } |
| 13                   | N<br>{ kgf } | 73.5<br>{ 7.5 }                    | 71.5<br>{ 7.3 } | 69.5<br>{ 7.1 } | 6.7<br>{ 0.68 }                     | 6.2<br>{ 0.63 } | 5.7<br>{ 0.58 } |
| 14                   | N<br>{ kgf } | 78.4<br>{ 8.0 }                    | 76.4<br>{ 7.8 } | 74.4<br>{ 7.6 } | 7.0<br>{ 0.71 }                     | 6.5<br>{ 0.66 } | 6.0<br>{ 0.61 } |
| 15                   | N<br>{ kgf } | 83.3<br>{ 8.5 }                    | 81.3<br>{ 8.3 } | 79.3<br>{ 8.1 } | 7.3<br>{ 0.74 }                     | 6.8<br>{ 0.69 } | 6.3<br>{ 0.64 } |



|                                 |                   |  |                  |                     |                   |
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【7. 圧着端子取り扱い上の注意事項 INSTRUCTION UPON USAGE OF CRIMP TERMINAL】

1. 保管する場合には、外装カートン表示に従って保管願います。縦置き又は、天地逆にて保管すると巻き緩みの原因になります。  
When storing crimp terminal, please follow the view of outer carton. Do not store in an upright position or upside down. It could loosen the terminal.

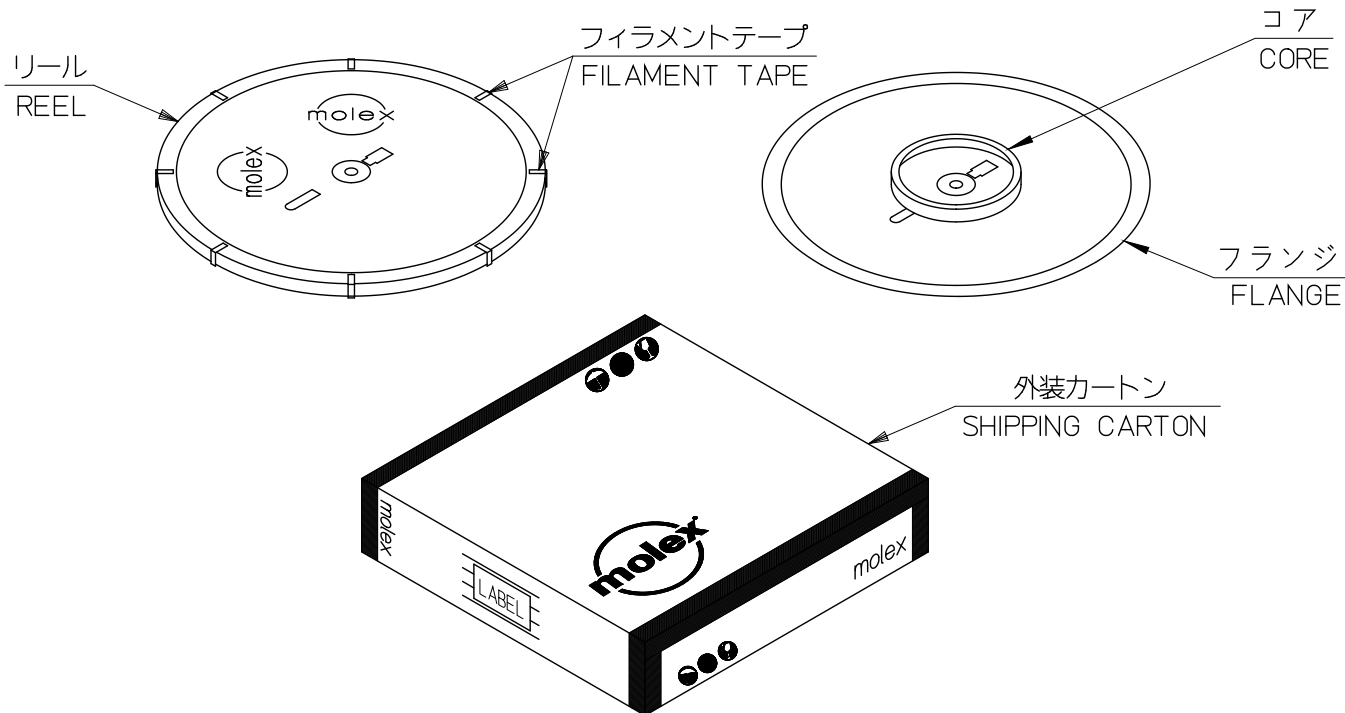
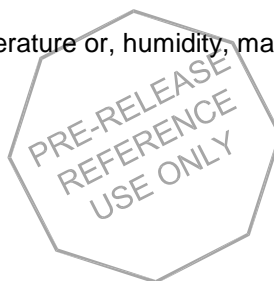


図1 端子梱包に関する各部名称  
FIG.1. NOMENCLATURE FOR THE TERMINAL PACKAGING

2. 保管環境に著しい高温・湿度がある場合、端子表面層に錆等の影響を及ぼす事がありますのでご注意願います。  
When storing the terminal in the significant temperature or, humidity, may be affected at the terminal surface.



|                                 |                   |  |                  |                     |
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3. 輸送、運搬時、カートン内リール数が規定梱包数量に満たない場合には、リールに衝撃を与えぬ様に緩衝材を入れガタつき防止を行って下さい。  
When number of reel in carton less than the prescribed quantity, prevent looseness with adding the cushion, during transport, conveyance.

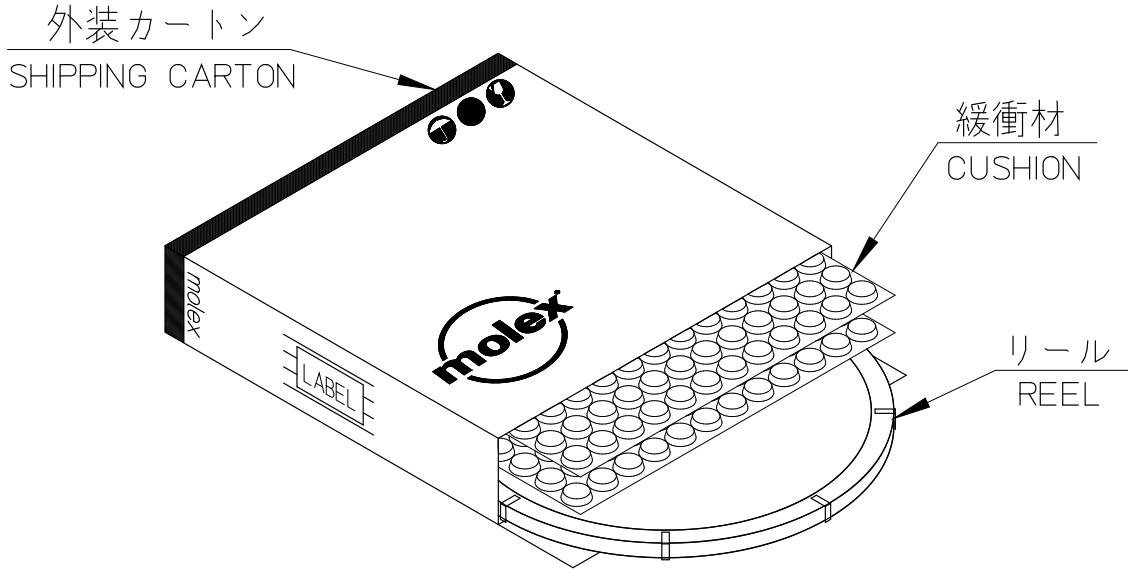


図2 カートン内リール数が規定梱包数量に満たない場合の梱包方法  
FIG.2 PACKAGING METHOD, IN CASE OF NUMBER OF REEL  
IN CARTON LESS THAN THE PRESCRIBED QUANTITY



|                                 |                   |  |                  |                     |
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4. カートンからリールを取り出す際は、両側フランジを持ち取り出して下さい。片面だけを掴んだ場合端子自重によりコア部からフランジ面が剥がれる恐れがあります。  
When removing the reel from the carton, please remove with holding the flange on both sides. Do not grab only one side. It could detach the flange from the core.

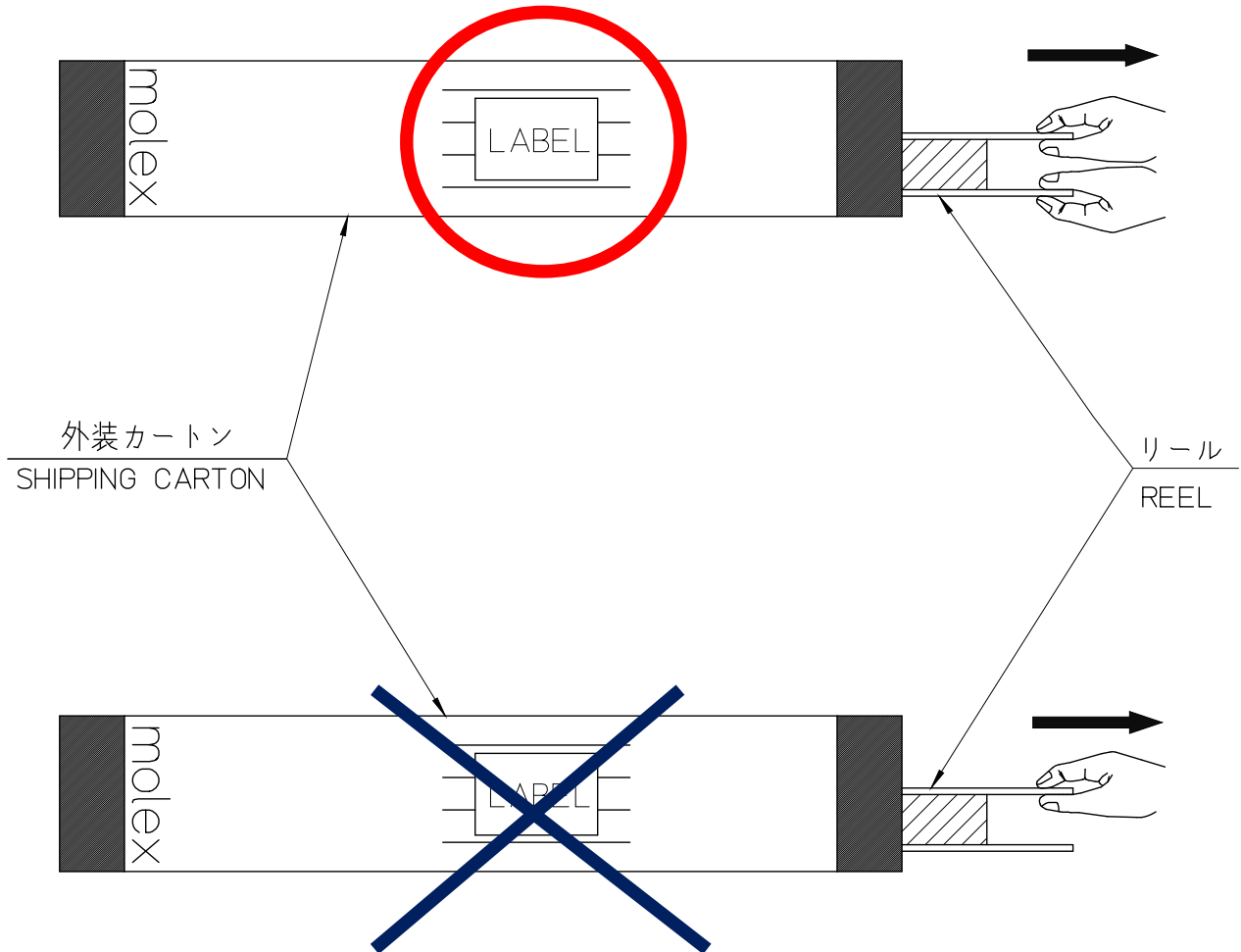


図3 リールの取り出し方法  
FIG.3 METHOD OF REMOVING THE REEL FROM THE CARTON



|                                 |                   |  |                  |                     |
|---------------------------------|-------------------|--|------------------|---------------------|
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5. カートンよりリールを取り出し保管される場合には、キャリア側を下側にして保管願います。  
 キャリア側を上にして、保管されますと端子自重により巻き緩みが発生する恐れがあります。  
 When storing the terminal with remove the reel from the carton, please keep carrier down side. Do not keep carrier up side. It could loosen the terminal.

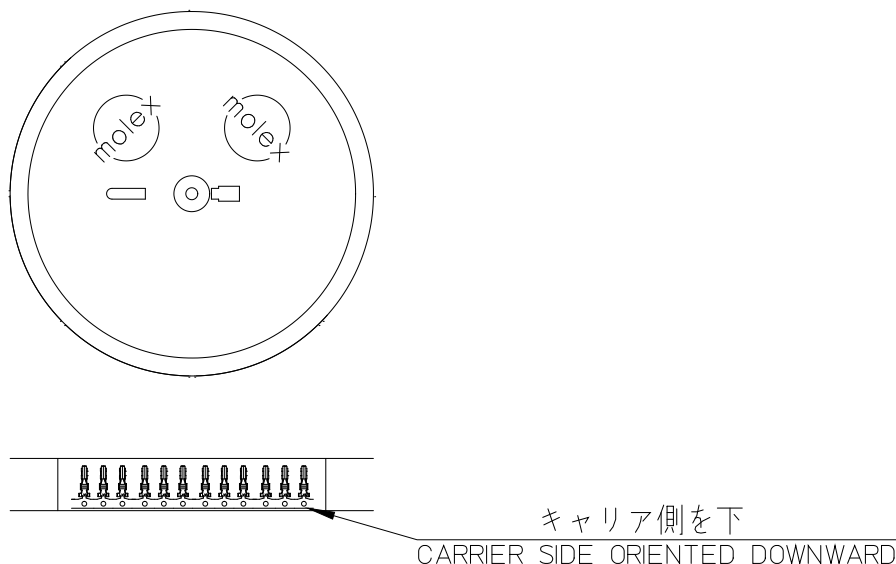
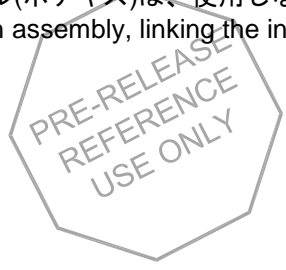


図4リール保管時の向き  
 FIG.4 DIRECTION OF THE REEL STORAGE

6. 圧着機へリールを長時間掛けた状態でいますと、端子自重により巻き緩みが発生する恐れがあります。  
 ご使用にならない場合には、中間紙で端子全周を2~3周巻いた後、巻き緩みが生じない様、中間紙先端、フランジ間のテープ止めをし、キャリア側を下にして保管願います。  
 Do not put the reel in the crimping machine for long period. It could loosen the terminal. When it is not used, after rolling interleaf twice, or three times into terminal all around, please keep carrier down side, with taping tip of the interleaf and flange.
7. 圧着仕様を満足する為に、当社推奨圧着機のご使用をお願い致します。  
 In order to meet the crimp specification, please use our recommended crimping machine.
8. 外装カートン組立及び、中間紙繋ぎにステープル(ホチキス)は、使用しないで下さい。  
 Stapler prohibited in whole area with outer carton assembly, linking the interleaf .



|                                 |                   |  |                  |                     |
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